

SOT1062-1

plastic low profile fine-pitch ball grid array package; 286 balls

8 February 2016

Package information

1. Package summary

Terminal position code	B (bottom)
Package type descriptive code	LFPGA286
Package type industry code	LFPGA286
Package style descriptive code	LFPGA (low profile fine-pitch ball grid array)
Package style suffix code	NA (not applicable)
Package body material type	P (plastic)
JEDEC package outline code	MO-205
Mounting method type	S (surface mount)
Issue date	28-1-2008

Table 1. Package summary

Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	14.9	-	15	15.1	mm
E	package width	14.9	-	15	15.1	mm
A	seated height	[tbd]	-	[tbd]	1.5	mm
A ₂	package height	0.95	-	1.03	1.1	mm
e	nominal pitch	-	-	0.8	-	mm
n ₂	actual quantity of termination	-	-	286	-	



2. Package outline

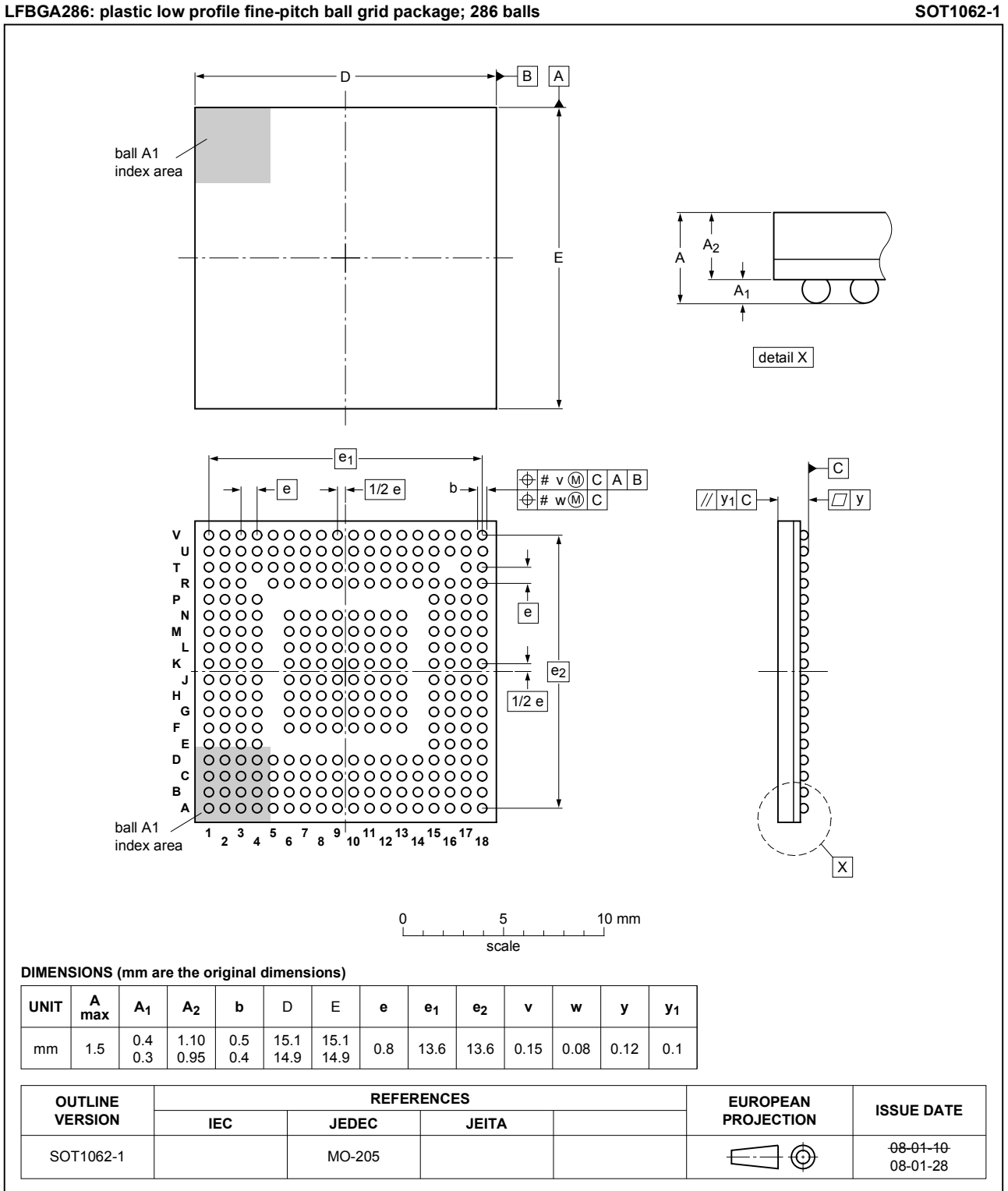


Fig. 1. Package outline LFBGA286 (SOT1062-1)

3. Legal information

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